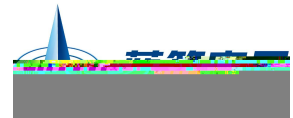


/ Revised record

A			W01		



/ Descriptions

800V 2.0A SMB

Surface Mount Superfast Recovery Rectifier, Reverse Voltage: 800V, Forward Current: 2.0A, SMB package.

/ Features

2011/65/EU RoHS

Glass Passivated Chip Superfast reverse recovery time, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications, Halogen free product.

/ Applications

General purpose.

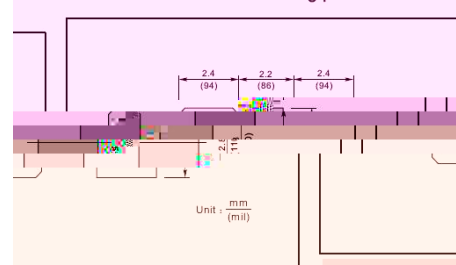
/ Equivalent Circuit



/ Pinning



The recommended mounting pad size



/ Marking

See Marking Instructions

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
		ES2AB	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}		

/ Electrical Characteristic Curve

Fig.1. Reverse Recovery Time Characteristic And Test Circuit Diagram

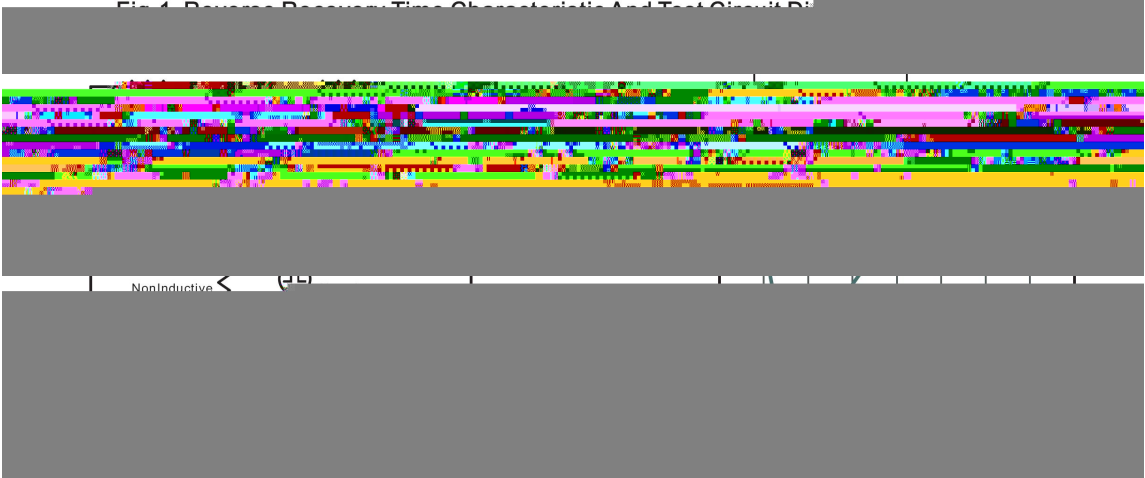


Fig.2. Maximum Average Forward Current Rating

Fig.3. Typical Reverse Characteristics

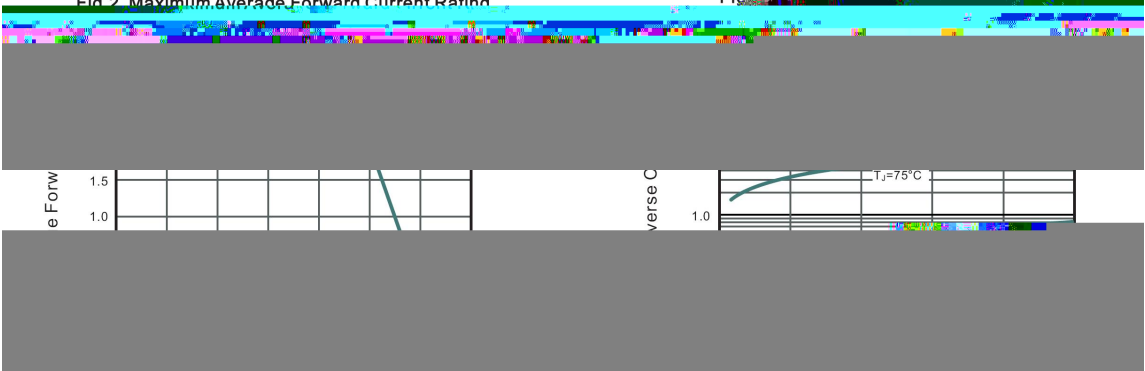


Fig.4. Typical Forward Characteristics

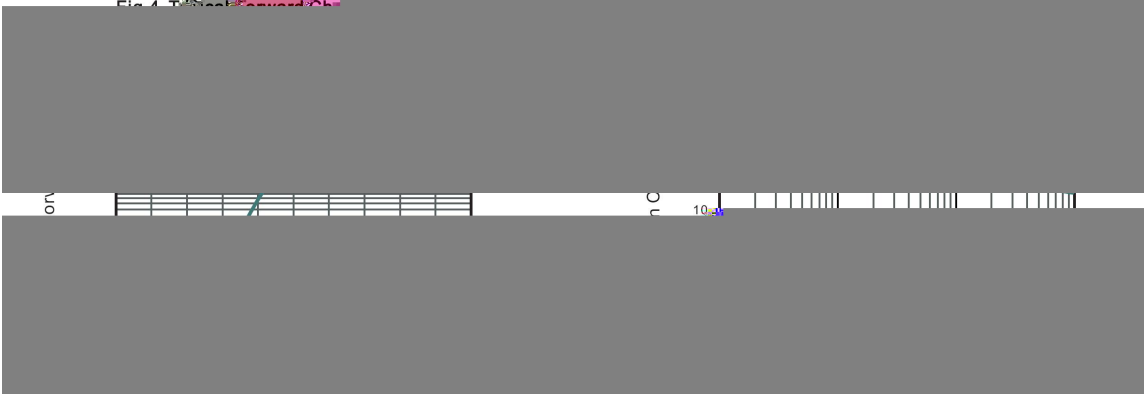
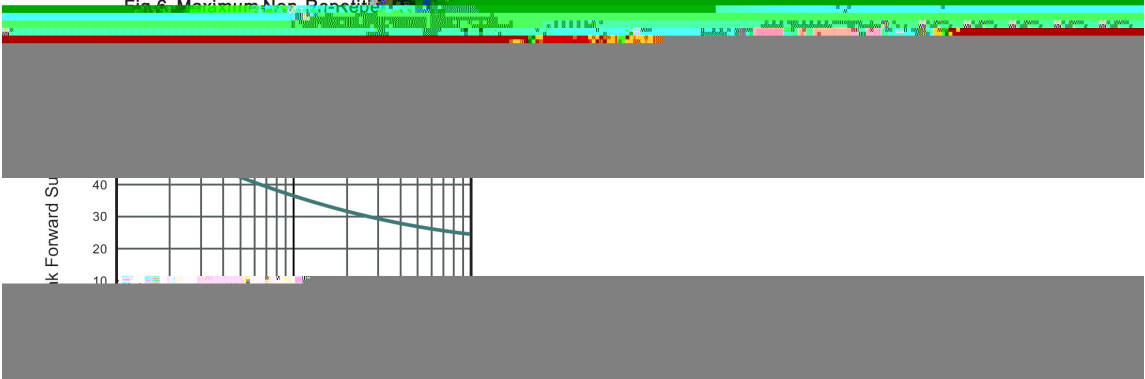
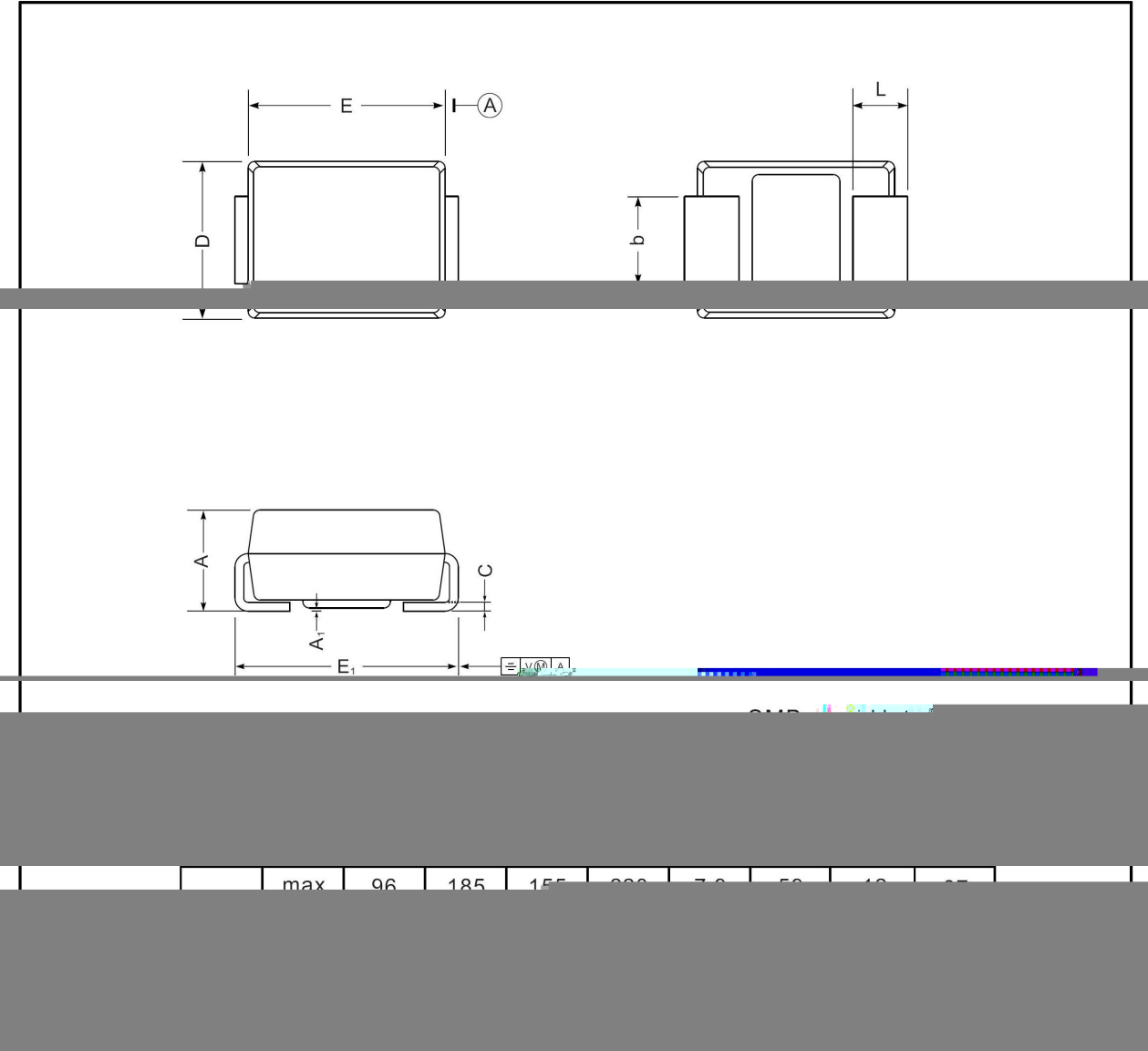


Fig.5. Maximum Non-Reversible Power

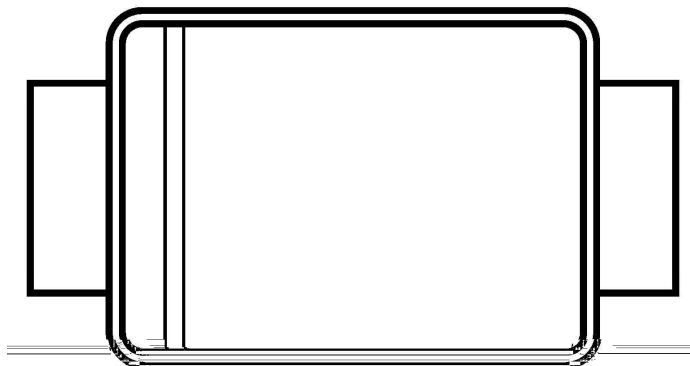


/ Package Dimensions

SMB



/ Marking Instructions



说明：

ES2K： 为型号代码

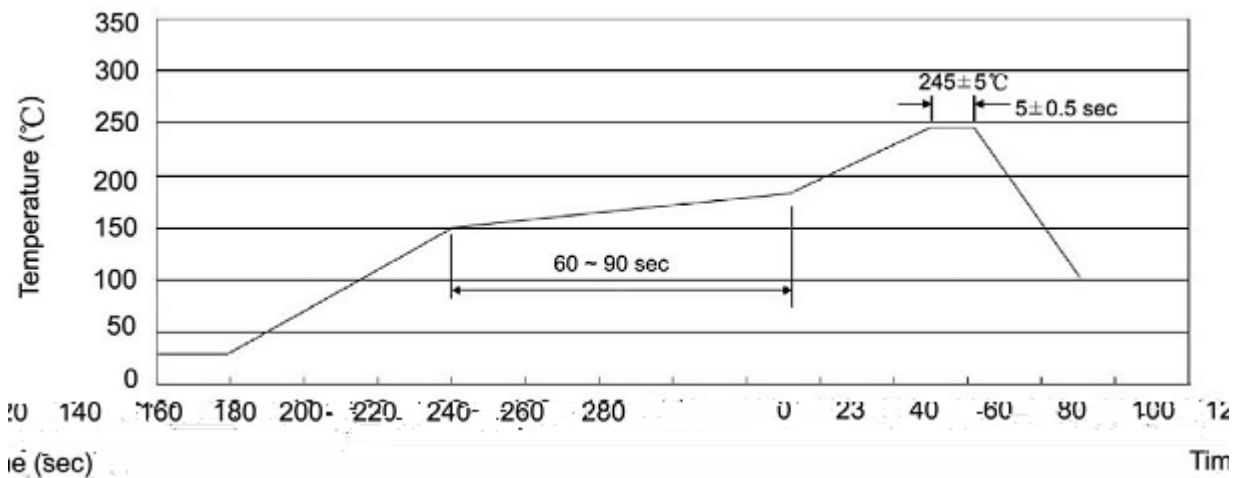
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

ES2K： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMB	3000	5	15000	5	75000	7" ×11	185X180X105	390X385X205

/ Notices